



- 10/100/1000 BaseT, Gigabit for LAN and other Ethernet Applications
- Transmit open circuit inductance (OCL): 350µH (MIN) @ 100KHz, 0.1VRMS with 8mA DC Bias
- RJ45 Jack cavity conforms to FCC rules and regulations Part 68, SUB Part F
- Standard Operating Temp: -40°C to +85°C
- Suitable for Reflow Solder at 265°C Max

Electrical Specifications @ 25°C

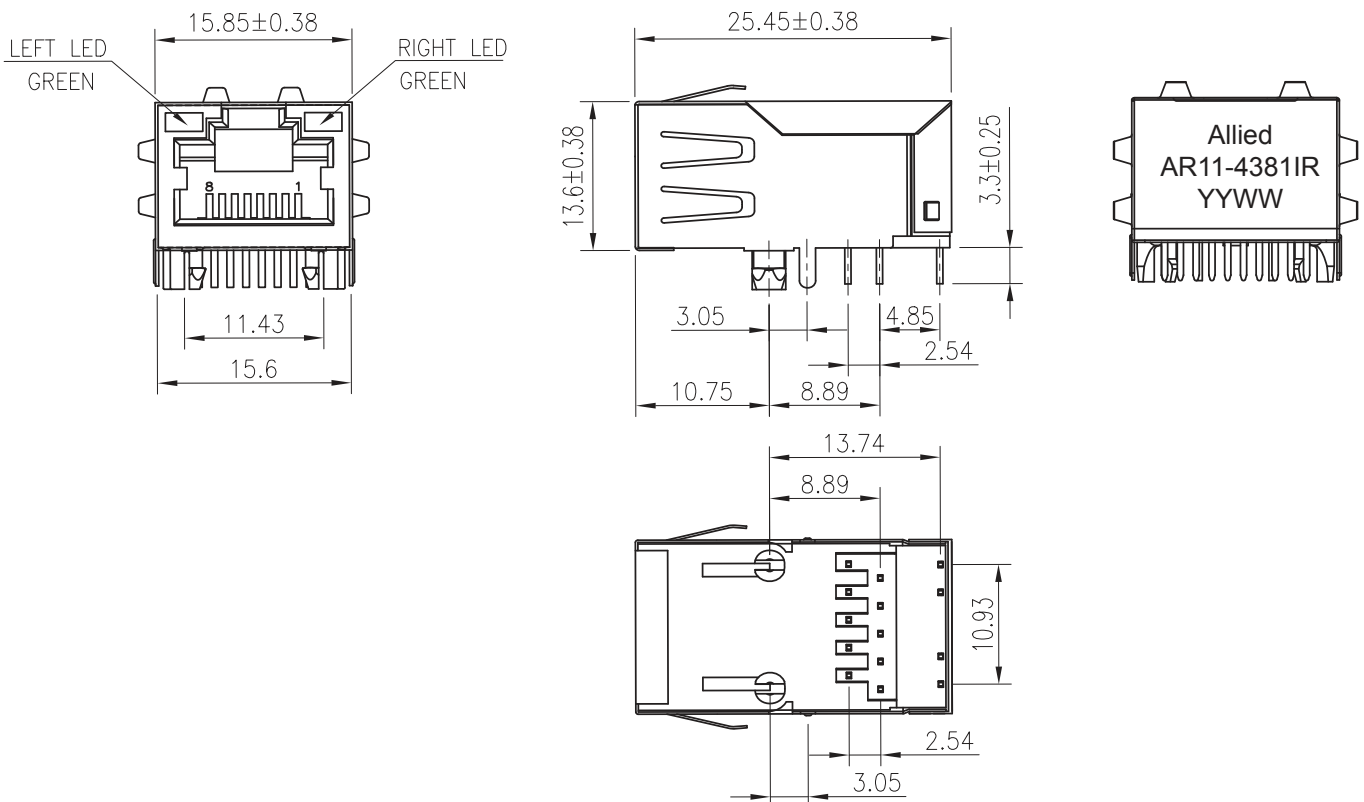
Part Number	OCL(µH Min) @ 100KHz, 0.1V With 8mA DC Bias	Turns Ratio chip: cable (±2%)	Insertion Loss (dB Max)	
			1-100MHz	100-125MHz
AR11-4381IR	350	1CT:1CT	-1.0	-1.2

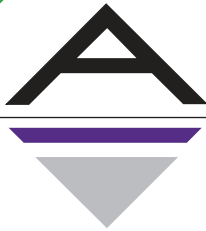
Electrical Specifications @ 25°C

Part Number	Return Loss (dB Min)		Cross Talk (dB Min)			Common Mode Rejection (dB Min)	Hi-Pot Test
	0.5-40MHz	40-100MHz	1~30MHz	30~80MHz	90~100MHz	1-100MHz	1mA, 60S
AR11-4381IR	-18	-12+20Log(f/80MHz) MIN	-35	-24	-25	-30	1500Vrms

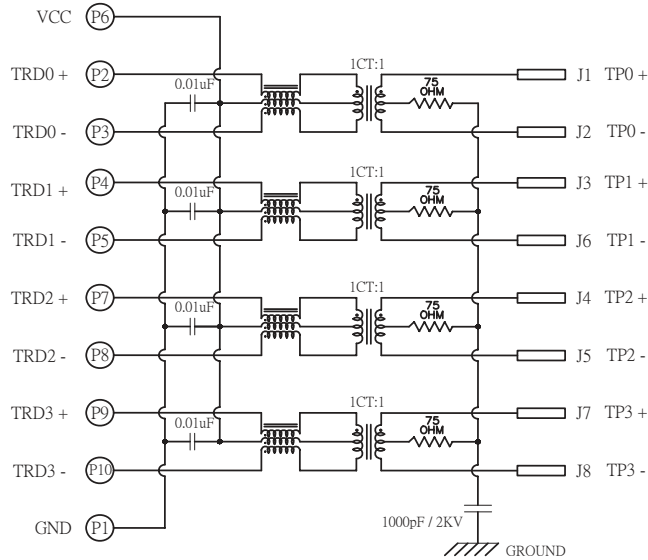
All specifications subject to change without notice.

MECHANICAL





SCHEMATICS



LEFT LED
11+ 12- GREEN

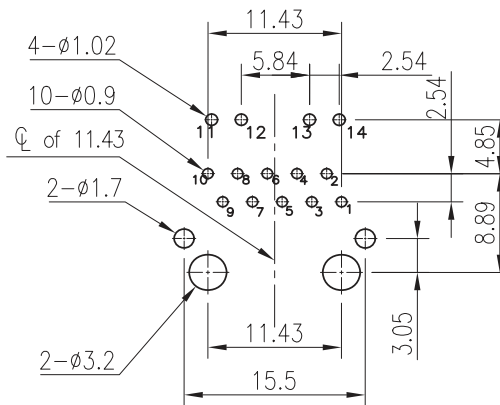
RIGHT LED
13+ 14- GREEN



STANDARD LED	WAVELENGTH	FORWARD VOLTAGE
GREEN	565nm	2.5V MAX

With a forward current of 20mA

PCB LAYOUT



RECOMMENDED PCB LAYOUT
TOLERANCE ±0.05mm(T=1.6mm)

NOTES

1. Shielded - 0.20mm Thickness Brass C2680 H. Plating Nickel 20u" min.
2. Housing - Plastic: LCP, Glass Fiber Filled UL94V-0, Color Black.
3. Contact Pin - Plastic: LCP, Glass Fiber Filled UL94V-0, Color Black. Pin: 0.35mm Thickness Phosphor Bronze C5210 EH. Plating: Nickel 30u"~60u" For All And Sn 100%, And Gold Plating 50u".
4. Insert Pin - Plastic: LCP, Glass Fiber Filled UL94V-0, Color Black. Pin: 0.35mm Thickness SUS430. Plating: 120u" min Sn All Over 30u"~60u" Nickel

**WAVE SOLDER PROFILE**

1. Peak temperature (T_p) : $260^{\circ}\text{C} \pm 5^{\circ}\text{C}$
2. Peak temperature (T_p) time: 10sec Max
3. Suitable for Reflow Solder at 265°C Max

